

Listing of Claims:

1. (currently amended) A heat sinkable package, comprising:
a power device package including at least one semiconductor chip having an active side and a non-active side, wherein the power device package is disposed in a product case and the non-active side of the semiconductor chip includes a heat sinkable surface positioned adjacent to and thermally connected to the [[a]] product case with a single thermal interface.
2. (currently amended) The heat sinkable package according to Claim 1, wherein the semiconductor chip is a power device package includes at least one flip chip.
3. (currently amended) The heat sinkable package according to Claim 2, wherein the ~~at least one~~ flip chip is positioned over a flexible circuit.
4. (original) The heat sinkable package according to Claim 3, wherein the flexible circuit is laminated to a ring carrier.
5. (original) The heat sinkable package according to Claim 3, wherein the flexible circuit is selected from the group consisting of copper, polyimide, and a thin FR-4 Core Material.
6. (original) The heat sinkable package according to Claim 2, wherein the power device package includes a thermoset epoxy resin that underfills high temperature balls of the flip chips.
7. (original) The heat sinkable package according to Claim 6, wherein the flexible circuit includes central passages and perimeter passages that permits the simultaneous underfilling and overmolding of the at least one flip chip.

8. (original) The heat sinkable package according to Claim 1, wherein the power device package includes a copper lead frame, a silicon integrated circuit, a copper lead frame wire bond input/output connected to the silicon integrated circuit by a wire and a gold ball bond.

9. (canceled)

10. (original) The heat sinkable package according to Claim 1 [[9]], wherein the thermal interface is selected from the group consisting of a metallic solder, a thermally conductive adhesive, a thermally conductive grease, and a thermal film.

11. (original) The heat sinkable package according to Claim 1, wherein the power device package is a ball grid array package.

12. (original) The heat sinkable package according to Claim 1, wherein the power device package is a quad-flat non-leaded package.

13 – 17. (canceled)

18 (new) The heat sinkable package according to claim 3 including an additional semiconductor chip having an active side and a non-active side with the non-active side having a heat sinkable surface positioned adjacent to and thermally connected to the product case with a single thermal interface, the heat sinkable surfaces of the semiconductor chips being substantially co-planar, and the active sides of the semiconductor chips being coupled to the flexible circuit in different, parallel planes.